

# ELECTRONIC ASSEMBLY STENCIL CLEANING

As PCB assemblies become denser and miniaturization drives electronic component size ever smaller, ensuring that solder paste deposits and volume transfer are consistent in the printing process has become more important. Proper solder paste transfer efficiency is especially critical for small pad features to reduce defects due to poor solder joints.

Choosing the best stencil cleaning method can be key. Whether it is manual (handwipe), an off-line cleaning machine process or on printer (under stencil wipe), KYZEN will work with you to select the best product to make sure you get the best print quality and best process yields.

## STENCIL CLEANING - OFFLINE

### SUGGESTED PRODUCTS:

#### KYZEN E5631

E5631 is a versatile, cost effective solution used in all types of stencil cleaning processes including spray-in-air, ultrasonic and understencil wipe systems. E5631 is compatible with stencil foil, epoxy adhesives, frames, and mesh as well as the materials of construction found in stencil cleaning equipment.

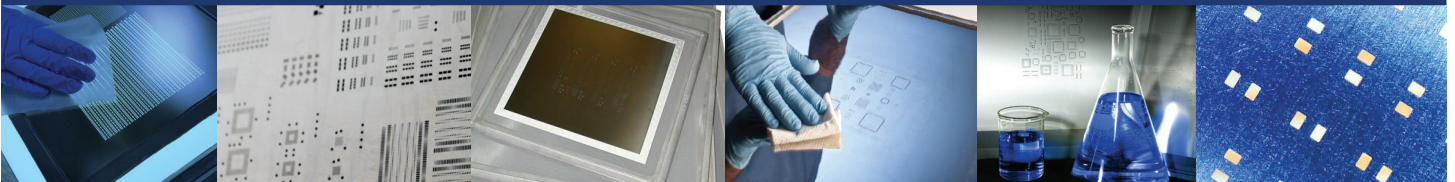
#### CYBERSOLV C8882

C8882 is an ideal wipe solvent that is non-toxic, is compatible with the stencil printer, rapidly dissolves a wide range of flux compositions and dries similar to IPA. The drying feature is a critical KYZEN stencil cleaning design factor.

### APPLICATIONS:

- Ultrasonic & Spray Equipment
- Semi-Automatic and Manual Cleaning
- Works Great at Low Concentrations
- Effective for A-Side Misprints
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Interact or Remove Nano Coatings

- Semi-Automatic and Manual Cleaning
- Fast Drying, Non-Flammable
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Interact or Remove Nano Coatings



## STENCIL CLEANING - UNDERSIDE WIPE, PRINTERS

### SUGGESTED PRODUCTS:

#### CYBERSOLV C8882

C8882 is an ideal wipe solvent that is non-toxic, is compatible with the stencil printer, rapidly dissolves a wide range of flux compositions and dries similar to IPA. The drying feature is a critical KYZEN stencil cleaning design factor.

#### KYZEN E5631J

E5631J is a ready-to-use solution for removing raw solder paste from stencils both in printers and offline stencil cleaning processes. E5631J cleans all types of raw solder pastes and it's compatible with all major printer brands.

### APPLICATIONS:

- Compatible with All Major Printer Brands
- Fast Drying, Non-Flammable
- Removes All Solder Paste Types
- Effectively Cleans Uncured Adhesives
- Does Not Interact or Remove Nano Coatings

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